

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L12	1	(depositing with metal with semiconductor adj device and substrate with first adj surface and second adj surface and electrolytic adj bath and first adj voltage with anode and metal adj ions and second adj layer and second adj voltage and sufficient and retain adj metal adj ions).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/16 13:04

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	45	"5662788"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/16 12:50
L2	7	"6171952"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/16 12:48
L3	5	"6753254"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/16 12:48
L4	12	"6144095"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/16 12:47
L5	12	"6144095"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/16 12:47
L6	4724	438/321,629,641,678,692.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/16 12:55
L7	421	6 and (metal metallic metallization) near3 (layer film) with (electroless\$3 electroplat\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/16 12:57

EAST Search History

L8	27	7 and (voltage) with (electroless\$3 electroplat\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/16 12:58
L9	1	10/820291	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/16 12:59
L12	1	(depositing with metal with semiconductor adj device and substrate with first adj surface and second adj surface and electrolytic adj bath and first adj voltage with anode and metal adj ions and second adj layer and second adj voltage and sufficient and retain adj metal adj ions).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/16 13:04